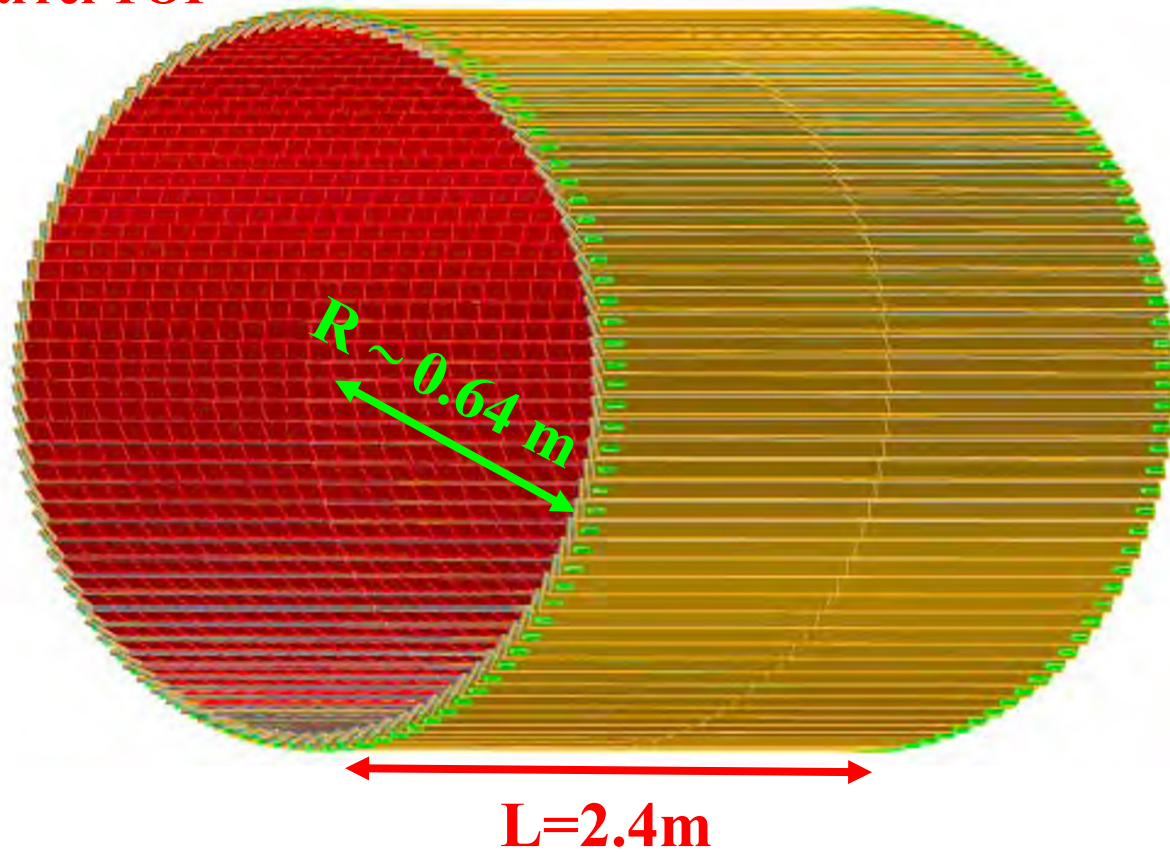
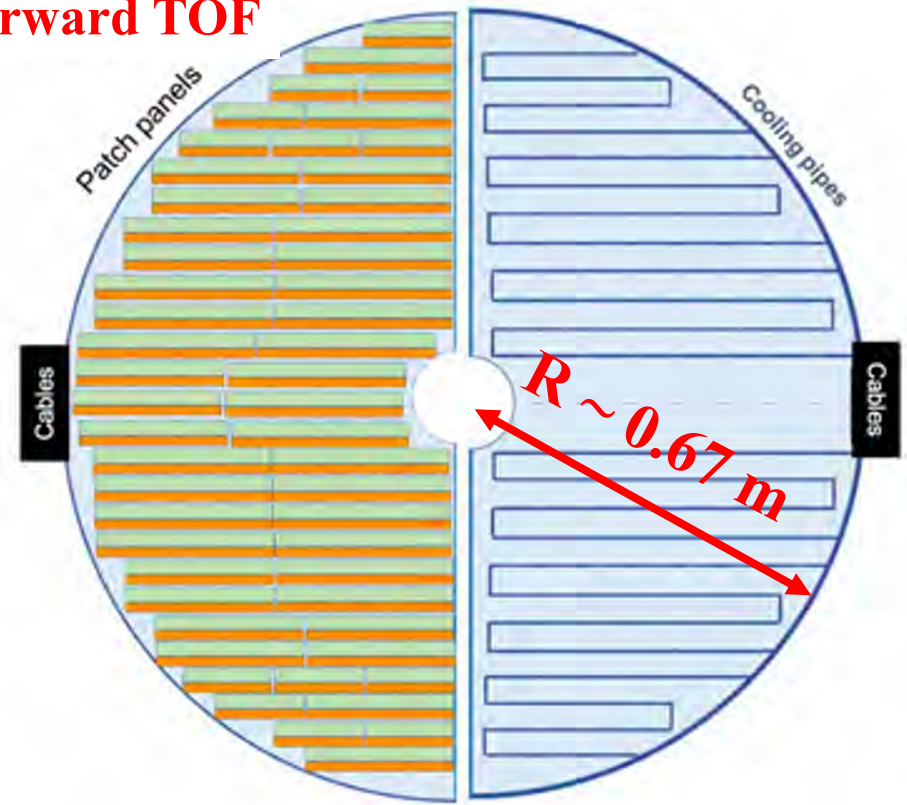


# AC-LGAD TOF Detector Requirements

## Barrel TOF



## Forward TOF



Detector	Area	Channel size	Channel number	Time resolution	Spatial resolution	Material budget
Barrel TOF	$\sim 10 \text{ m}^2$	0.5mm x 10mm	$\sim 2.2 \text{ M}$	35 ps	30 $\mu\text{m}$ in $r\cdot\phi$	0.01 X0
Forward TOF	$\sim 1.4 \text{ m}^2$	0.5mm x 0.5mm	$\sim 5.6 \text{ M}$	25 ps	30 $\mu\text{m}$ in x and y	0.05 X0

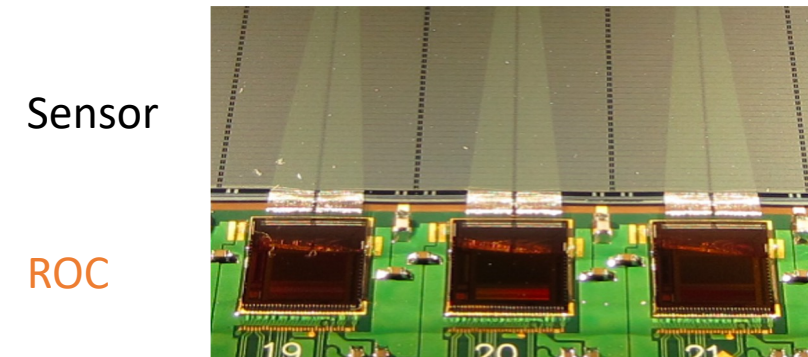
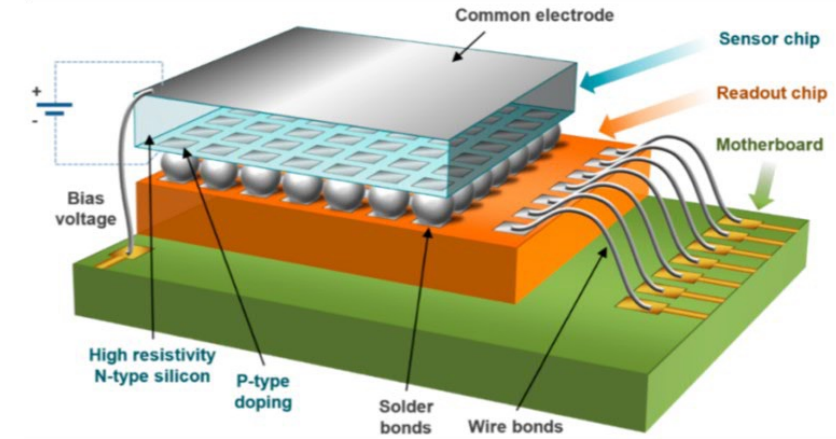
# TOF Requirements on Frontend ASIC

## • FTOF Requirements

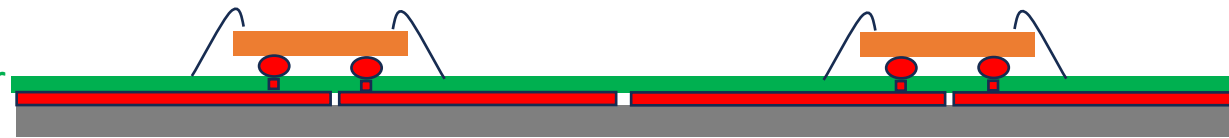
- sensor bonding: **bump-bonding**
- pixel size  **$0.5 \times 0.5 \text{ mm}^2$**  (larger pixels being studied)
- pixel array  **$32 \times 32$**  (TBD)
- low power consumption  $\leq 1 \text{ mW/channel}$
- low jitter  $\leq 15 \text{ ps}$  for MIP@12 fC
- sensitivity to low charge (1-2 fC)
- time resolution (sensor+ASIC+clock)  $\leq 25 \text{ ps}$
- spatial resolution  $\leq 30 \text{ microns}$

## • BTOF Requirements

- sensor bonding: **wire-bonding or bump-bonding** (TBD)
- strip size  **$0.5 \times 10 \text{ mm}^2$**
- strip array  **$64 \times 2$**  (TBD)
- low power consumption  $\leq 1 \text{ mW/channel}$
- low jitter  $\leq 15 \text{ ps}$  for MIP@12 fC
- sensitivity to low charge (1-2 fC)
- time resolution (sensor+ASIC +clock)  $\leq 35 \text{ ps}$
- spatial resolution  $\leq 30 \text{ microns}$



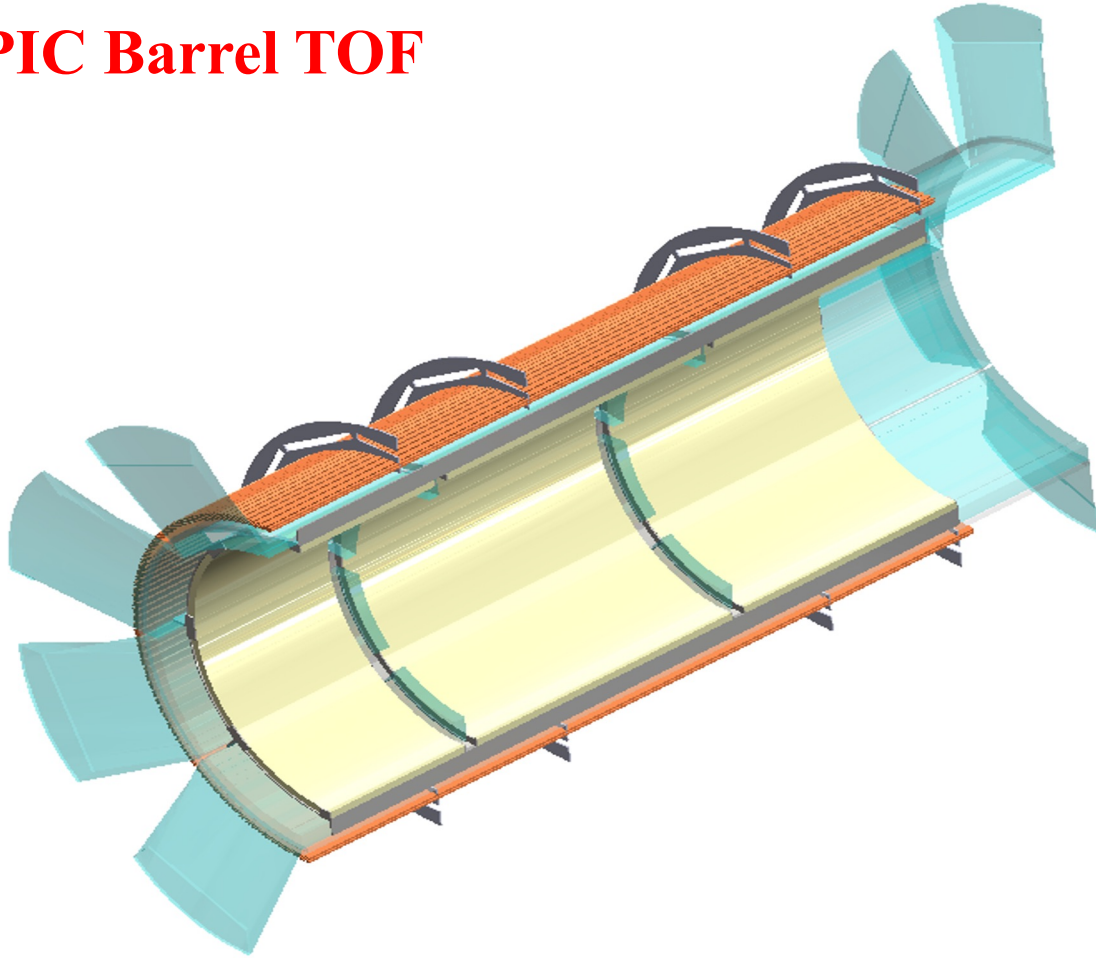
ROC  
Interposer  
Sensor



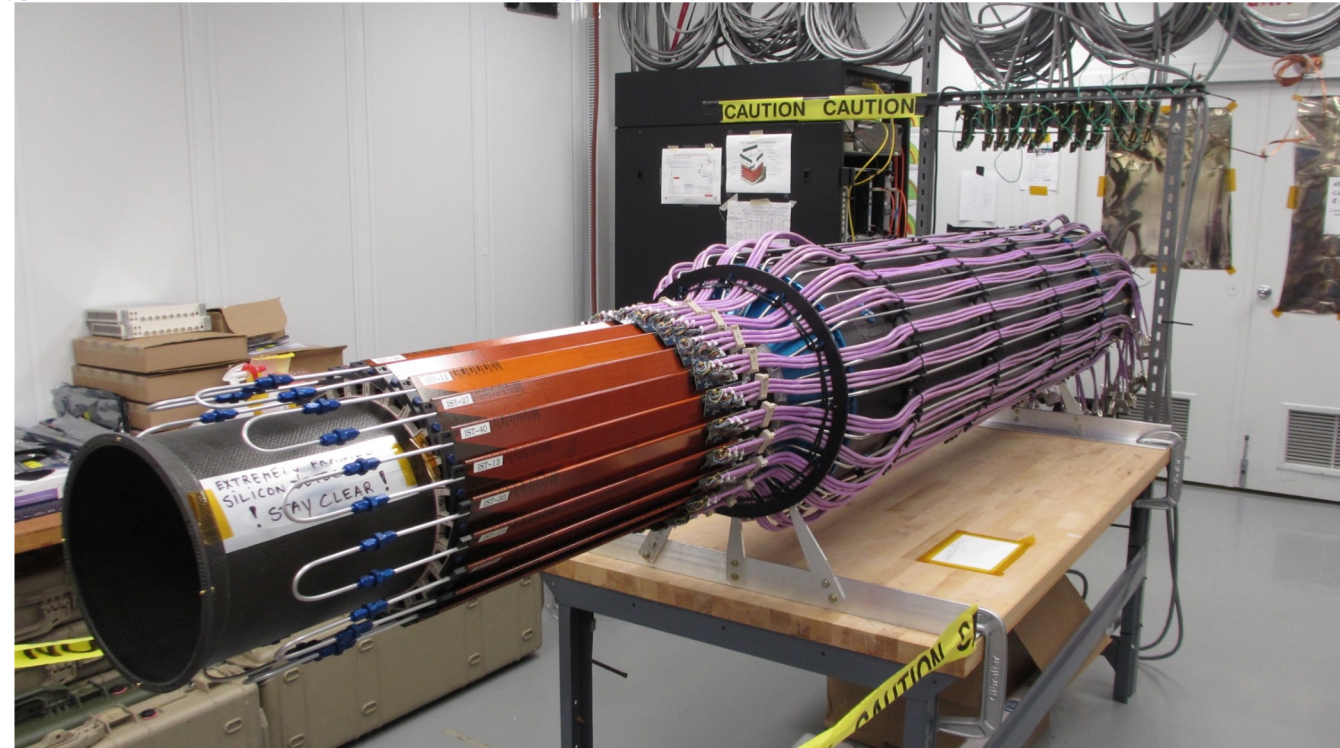


# BTOF Detector Layout

## ePIC Barrel TOF

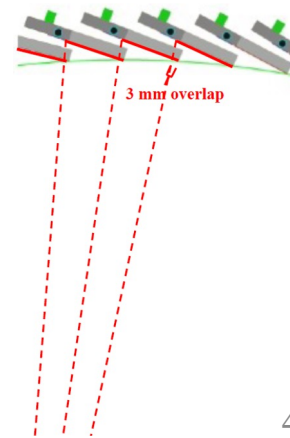


## STAR Intermediate Silicon Tracker

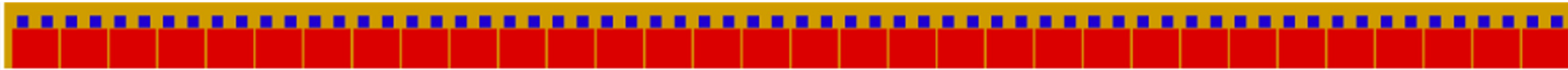
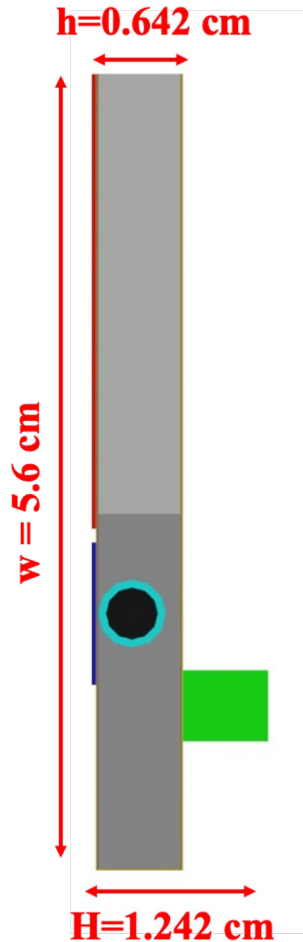


ePIC BTOF follows cylindrical silicon tracker design (e.g. STAR IST)

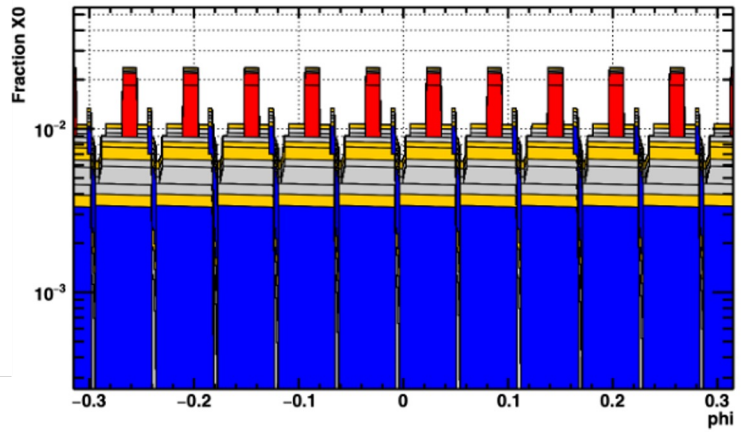
- Tilted stave modules overlap in phi to fully cover the azimuthal  $2\pi$  angle
- Readout boards connected to the end of staves are outside of the BTOF acceptance (see next talk)
- Cooling tubes with liquid coolant at room temperature to take the heat generated by frontend ASIC



# BTOF Detector Module Conceptual Design

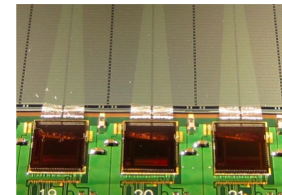
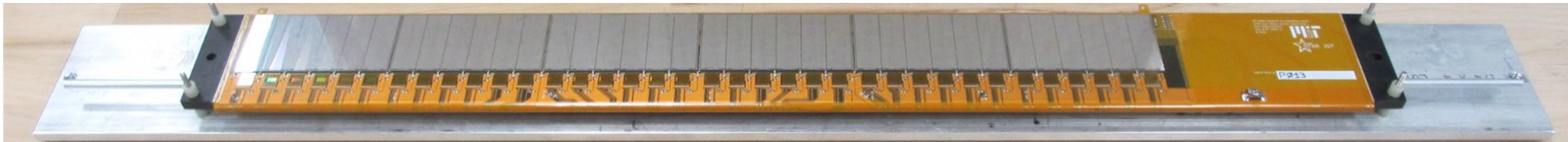


- **64 AC-LGAD strip sensors**, each  $3.2 \times 4 \text{ cm}^2$  read out by **2 ASICs**
- **Low mass flexible Kapton PCB** distributes power and I/O signals from **connector**
- **Liquid coolant in Al tube** embedded in CF light-weight structure for heat removal



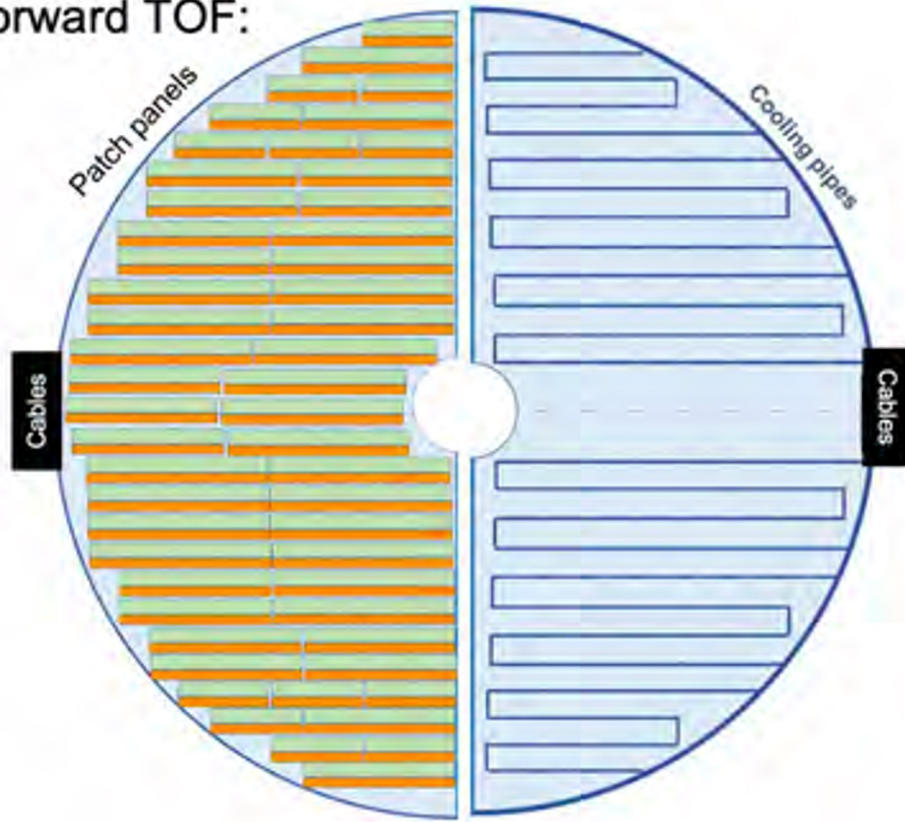
144 modules, each with 2 readout boards with 2 LV+HV cables, 2 DAQ fiber, and 1 cooling line  
Power consumption:  $\sim 4 \text{ kW}$  (2.4kW for ASIC, 1 kW for DC-DC, 0.6kW for sensors+cable)  
Total weight:  $\sim 70 \text{ kG}$

**STAR IST**

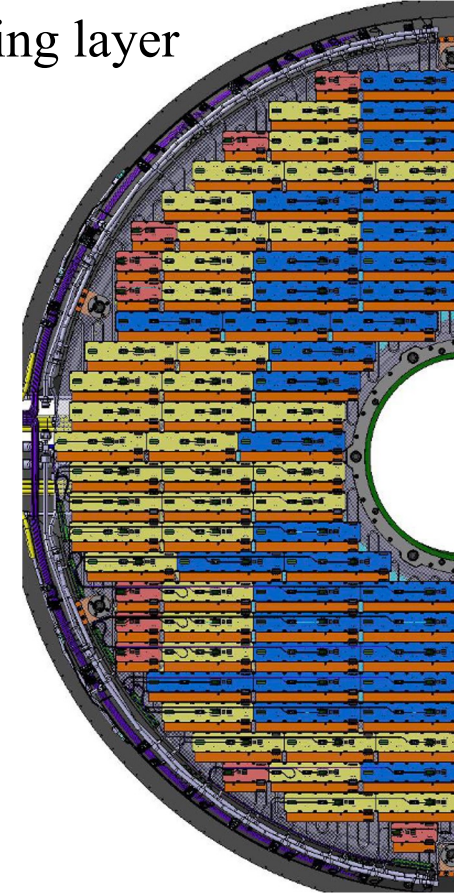


# FTOF Detector Layout

Forward TOF:



CMS endcap timing layer



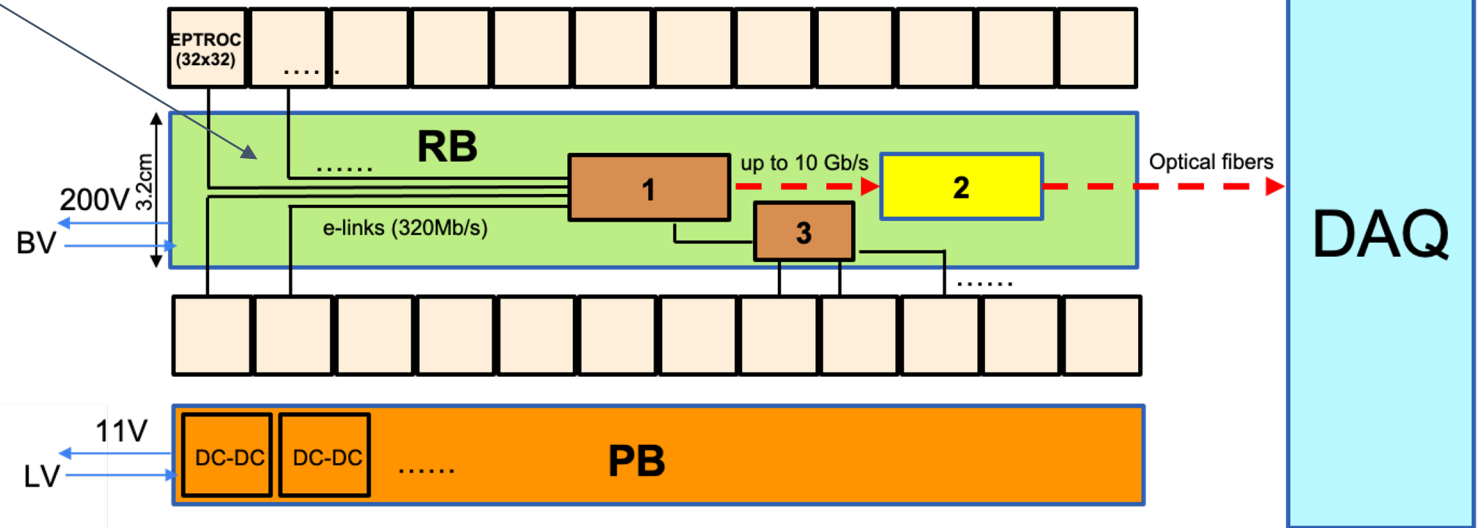
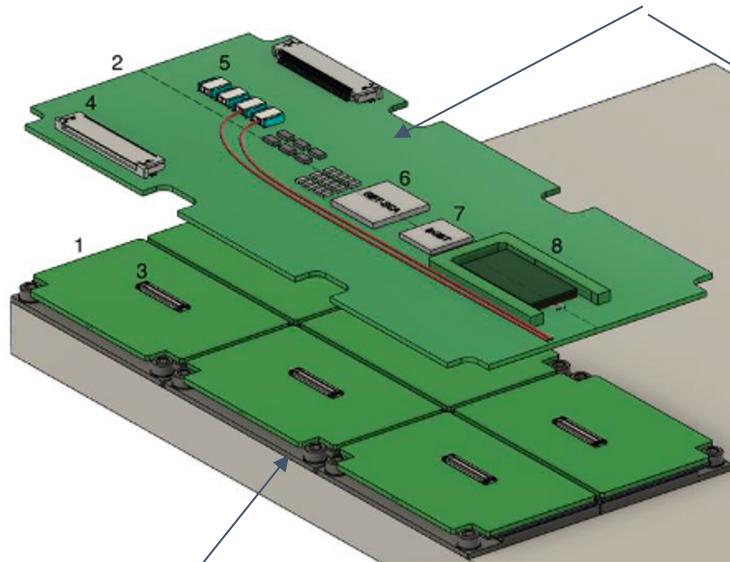
Forward TOF layout, based on the CMS ETL design:

- Two halves DEEs made of light-weight (carbon fiber) support structure, tiled by rectangular modules of three types with different lengths
- Cooling tubes with coolant at room temperature to take the heat generated by frontend ASICs and other electronic elements

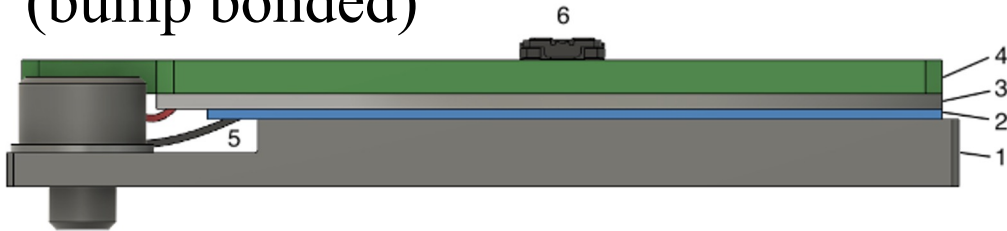
# FTOF Detector Module Conceptual Design

Readout Board

- 1: data transceiver FPGA chip
- 2: optical link module (e.g., CERN VTRx+)
- 3: slow control for monitoring



LGADs+EICROC  
(bump bonded)



212 readout boards, each has: 1 fiber to DAQ, 2 LV cables (1 supply, 1 return) and 2 BV cables (1 supply, 1 return)

Power consumption: ~13 kW (8.5kW for ASIC, 3.5 kW for DC-DC, 1kW for sensors+cable)

- Considering  $0.7 \times 0.7 \text{ mm}^2$  sensor design, which reduces the power budget by ~50%